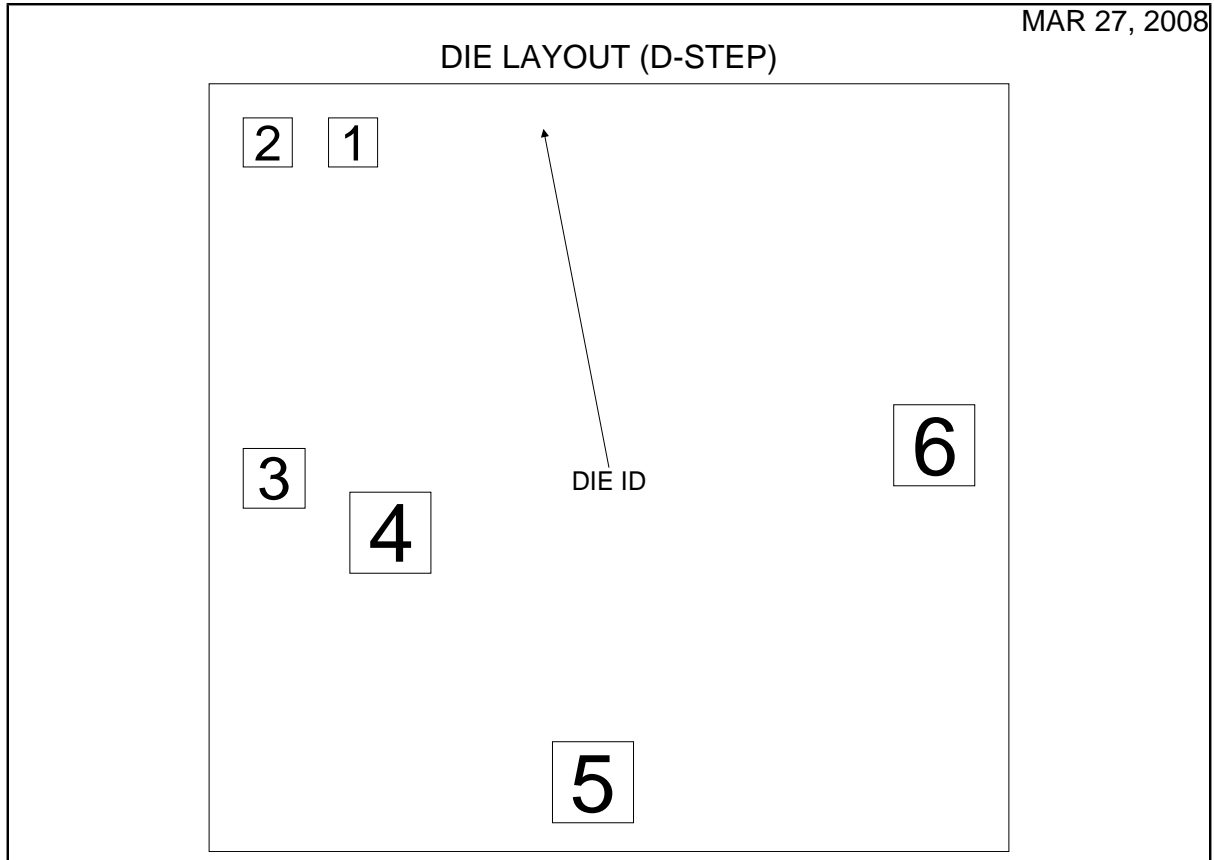


LM120HG-5 MD8 MCD2800A
SERIES 3-TERMINAL NEGATIVE REGULATORS



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM056D	Bond Pad Opening Size (min)	193.04µm x 193.04µm
Die Step	D	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	150mm	Back Side Metal	Gold
Die Size (Drawn)	1905.0µm x 1828.8µm 75.0mils x 72.0mils	Back Side Connection	INPUT
Thickness	254µm Nominal		
Min Pitch	765µm		

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

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Die Bond Pad Coordinate Locations(D-Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	
NC	1	-609	774	116	x	116
NC	2	-812	774	116	x	116
NC	3	-797	-25	147	x	142
OUTPUT	4	-520	-154	193	x	193
INPUT	5	-38	-749	193	x	193
GND	6	774	53	193	x	193

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